Specifications

Material
- Insulator: High Temp. Plastic UL 94V-0, Black
- Contact: Copper Alloy (T=0.15mm)
- Shell: Stainless Steel (T=0.30mm)
- Inner Ground Cover Shell: Stainless Steel (T=0.10mm)

Plating
- Contact: Gold Flash over 50µ" min. Nickel
- Solder Tails: 80µ" min. Matte Tin over 50µ" min. Nickel
- Shell: 50µ" min. Nickel

Electrical
- Current Rating: 3.00A collectively for VBUS pins
  4.25A collectively for GND pins
  1.25A for B5 pin
  0.25A per pin for all other pins
- Voltage Rating: 20V DC
- Contact Resistance: 40mΩ max initial.
  50mΩ max after test
- Dielectric Withstanding Voltage: 100V AC
- Insulation Resistance: 100MΩ min

Mechanical & Environmental
- Operating Temperature: -40°C to 85°C
- Mating Force: 5 to 20 N.
- Unmated Force: 6 to 20 N after test
- Durability: 10,000 cycles

Ordering Grid

<table>
<thead>
<tr>
<th>Pin</th>
<th>Signal</th>
<th>Mating Sequence</th>
<th>Pin</th>
<th>Signal</th>
<th>Mating Sequence</th>
</tr>
</thead>
<tbody>
<tr>
<td>A1</td>
<td>GND</td>
<td>First</td>
<td>B12</td>
<td>GND</td>
<td>First</td>
</tr>
<tr>
<td>A4</td>
<td>VBUS</td>
<td>First</td>
<td>B2</td>
<td>VBUS</td>
<td>First</td>
</tr>
<tr>
<td>A5</td>
<td>CC1</td>
<td>Second</td>
<td>B8</td>
<td>SBU2</td>
<td>Second</td>
</tr>
<tr>
<td>A6</td>
<td>Dip1</td>
<td>Second</td>
<td>B7</td>
<td>Dn2</td>
<td>Second</td>
</tr>
<tr>
<td>A7</td>
<td>Dn1</td>
<td>Second</td>
<td>B6</td>
<td>Dip2</td>
<td>Second</td>
</tr>
<tr>
<td>A8</td>
<td>SBU1</td>
<td>Second</td>
<td>B5</td>
<td>CC2</td>
<td>Second</td>
</tr>
<tr>
<td>A9</td>
<td>VBUS</td>
<td>First</td>
<td>B4</td>
<td>VBUS</td>
<td>First</td>
</tr>
<tr>
<td>A12</td>
<td>GND</td>
<td>First</td>
<td>B1</td>
<td>GND</td>
<td>First</td>
</tr>
</tbody>
</table>

Contact Plating
- GF = Gold Flash

Packing Options
- A = Tape & Reel (700 per reel)

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www.gct.co

Part Number
- USB4085

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Detail C

Scale: 2.1
Recommended PCB Layout

As viewed from component side  Tolerance:±0.05mm

Solder Area  Component Outline
Notes:
Peeling off force of top tape: 0.1-1.3N (Peeling direction as shown)

Materials:
Carrier Tape: Polystyrene (PS)
Top Tape: PE
Reel Tape: Polystyrene (PS)
Bag: PE